10758651_CLS
Most Frequently Occurring Classifications of Patents Returned From A Search of 10758651 on July 28, 2004

Original Classifications

9	250/307
5	250/311
4	250/492.21
2	430/619
2	438/14

Cross-Reference Classifications

6	250/307
5	250/309
5	250/311
5	250/492.21
4	216/60
3	204/192.34
3	250/306
3	250/310
3	250/442.11
3	250/492.2
2	204/298.36
2	216/39
2	216/66
2	216/85
2	250/492.1
2	250/559.33
2	438/16
2	438/706
2	438/712

Combined Classifications

15	250/307
10	250/311
9	250/492.21
6	250/309
4	216/60
4	250/310
4	250/442.11
3	204/192.34
3	250/306
3	250/492.2
2	204/298.36
2	216/33
2	216/39
2	216/59
2	216/66

2 216/85
2 219/693
2 219/745
2 250/492.1
2 250/559.33
2 324/751
2 428/408
2 430/619
2 438/14
2 438/16
2 438/706
2 438/712

10758651_CLSTITLES

Titles of Most Frequently Occurring Classifications of Patents Returned

From A Search of 10758651 on July 28, 2004

15 250/307 (9 OR, 6 XR)
Class 250 : RADIANT ENERGY
250/306 INSPECTION OF SOLIDS OR LIQUIDS BY CHARGED PARTICLES
250/307 .Methods

10 250/311 (5 OR, 5 XR)
Class 250 : RADIANT ENERGY
250/306 INSPECTION OF SOLIDS OR LIQUIDS BY CHARGED PARTICLES
250/311 .Electron microscope type

9 250/492.21 (4 OR, 5 XR)
Class 250 : RADIANT ENERGY
250/492.1 IRRADIATION OF OBJECTS OR MATERIAL
250/492.2 .Irradiation of semiconductor devices
250/492.21 ..Ion bombardment

6 250/309 (1 OR, 5 XR)
Class 250 : RADIANT ENERGY
250/306 INSPECTION OF SOLIDS OR LIQUIDS BY CHARGED PARTICLES
250/309 .Positive ion probe or microscope type

4 216/60 (0 OR, 4 XR)
Class 216 : ETCHING A SUBSTRATE: PROCESSES
216/58 GAS PHASE ETCHING OF SUBSTRATE
216/59 .With measuring, testing, or inspecting
216/60 ..By optical means or of an optical property

4 250/310 (1 OR, 3 XR)
Class 250 : RADIANT ENERGY
250/306 INSPECTION OF SOLIDS OR LIQUIDS BY CHARGED PARTICLES
250/310 .Electron probe type

4 250/442.11 (1 OR, 3 XR)
Class 250 : RADIANT ENERGY
250/306 INSPECTION OF SOLIDS OR LIQUIDS BY CHARGED PARTICLES
250/440.11 .Analyte supports
250/442.11 ..With object moving or positioning means

3 204/192.34 (0 OR, 3 XR)
Class 204 : CHEMISTRY: ELECTRICAL AND WAVE ENERGY
204/192.1 .Coating, forming or etching by sputtering
204/192.32 ..Sputter etching
204/192.34 ...Ion beam etching (e.g., ion milling, etc.)

3 250/306 (0 OR, 3 XR)
Class 250 : RADIANT ENERGY
250/306 INSPECTION OF SOLIDS OR LIQUIDS BY CHARGED PARTICLES

3 250/492.2 (0 OR, 3 XR)
Class 250 : RADIANT ENERGY
250/492.1 IRRADIATION OF OBJECTS OR MATERIAL
250/492.2 .Irradiation of semiconductor devices

2 204/298.36 (0 OR, 2 XR)
Class 204 : CHEMISTRY: ELECTRICAL AND WAVE ENERGY
204/193 APPARATUS
204/298.01 .Coating, forming or etching by sputtering
204/298.31 ..Etching
204/298.36 ...Beam or directed flux etching (e.g., ion beam, etc.)

2 216/33 (1 OR, 1 XR)
Class 216 : ETCHING A SUBSTRATE: PROCESSES
216/33 ADHESIVE OR AUTOGENOUS BONDING OF TWO OR MORE SELF-SUSTAINING PREFORMS WHEREIN AT LEAST T
WO OF THE
PREFORMS ARE NOT INTENDED TO BE REMOVED (E.
G.,
PREFABRICATED BASE, ETC.)

2 216/39 (0 OR, 2 XR)
Class 216 : ETCHING A SUBSTRATE: PROCESSES
216/39 FORMING GROOVE OR HOLE IN A SUBSTRATE WHICH IS SUBSEQUENTLY FILLED OR COATED

2 216/59 (1 OR, 1 XR)
Class 216 : ETCHING A SUBSTRATE: PROCESSES
216/58 GAS PHASE ETCHING OF SUBSTRATE
216/59 .With measuring, testing, or inspecting

2 216/66 (0 OR, 2 XR)
Class 216 : ETCHING A SUBSTRATE: PROCESSES
216/58 GAS PHASE ETCHING OF SUBSTRATE
216/63 .Application of energy to the gaseous etchant

or to the substrate being etched
216/66 ..Using ion beam, ultraviolet, or visible ligh
t

2 216/85 (0 OR, 2 XR)
Class 216 : ETCHING A SUBSTRATE: PROCESSES
216/83 NONGASEOUS PHASE ETCHING OF SUBSTRATE
216/84 .With measuring, testing, or inspecting
216/85 ..By optical means or of an optical property

2 219/693 (1 OR, 1 XR)
Class 219 : ELECTRIC HEATING
219/678 MICROWAVE HEATING
219/690 .Waveguide applicator
219/691 ..Slotted
219/693 ...Having load passage

2 219/745 (1 OR, 1 XR)
Class 219 : ELECTRIC HEATING
219/678 MICROWAVE HEATING
219/745 .Field modification

2 250/492.1 (0 OR, 2 XR)
Class 250 : RADIANT ENERGY
250/492.1 IRRADIATION OF OBJECTS OR MATERIAL

2 250/559.33 (0 OR, 2 XR)
Class 250 : RADIANT ENERGY
250/200 PHOTOCELLS; CIRCUITS AND APPARATUS
250/559.01 .With circuit for evaluating a web, strand, strip, or sheet
250/559.29 ..Measuring position
250/559.33 ...With robotics

2 324/751 (1 OR, 1 XR)
Class 324 : ELECTRICITY: MEASURING AND TESTING
324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF ELECTRIC COMPONENTS
324/537 .Of individual circuit component or element
324/750 ..System sensing fields adjacent device under test (DUT)
324/751 ...Using electron beam probe

2 428/408 (1 OR, 1 XR)
Class 428 : STOCK MATERIAL OR MISCELLANEOUS ARTICLES
428/408 SELF-SUSTAINING CARBON MASS OR LAYER WITH IMPREGNANT OR OTHER LAYER

2 430/619 (2 OR, 0 XR)
Class 430 : RADIATION IMAGERY CHEMISTRY: PROCESS, COMPOSITION, OR PRODUCT THEREOF
430/495.1 RADIATION SENSITIVE PRODUCT
430/564 .Silver compound sensitizer containing
430/617 ..Silver compound other than halide, per se, or composition for thermographic process process
430/618 ...Organic silver compound containing
430/619 ....And inorganic silver compound

2 438/14 (2 OR, 0 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/14 WITH MEASURING OR TESTING

2 438/16 (0 OR, 2 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/14 WITH MEASURING OR TESTING
438/16 .Optical characteristic sensed

2 438/706 (0 OR, 2 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/689 CHEMICAL ETCHING
438/706 .Vapor phase etching (i.e., dry etching)

2 438/712 (0 OR, 2 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/689 CHEMICAL ETCHING
438/706 .Vapor phase etching (i.e., dry etching)
438/707 ..Utilizing electromagnetic or wave energy
438/710 ...By creating electric field (e.g., plasma, glow discharge, etc.)
438/712 ....Reactive ion beam etching (i.e., RIBE)